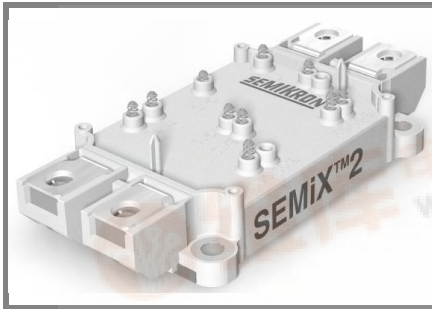


SEMIX 302GB176HDS



SEMIX[®] 2s

Trench IGBT Modules

SEMIX 302GB176HDS

Target Data

Features

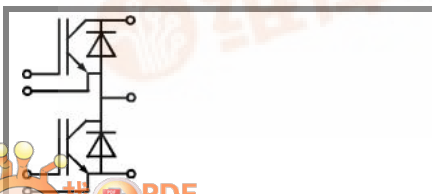
- Homogeneous Si
- Trench = Trenchgate technology
- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability

Typical Applications

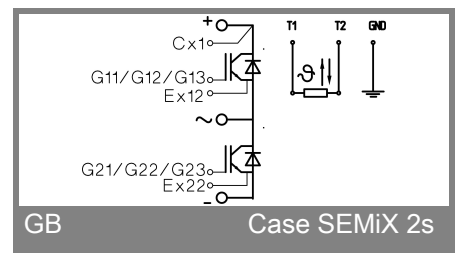
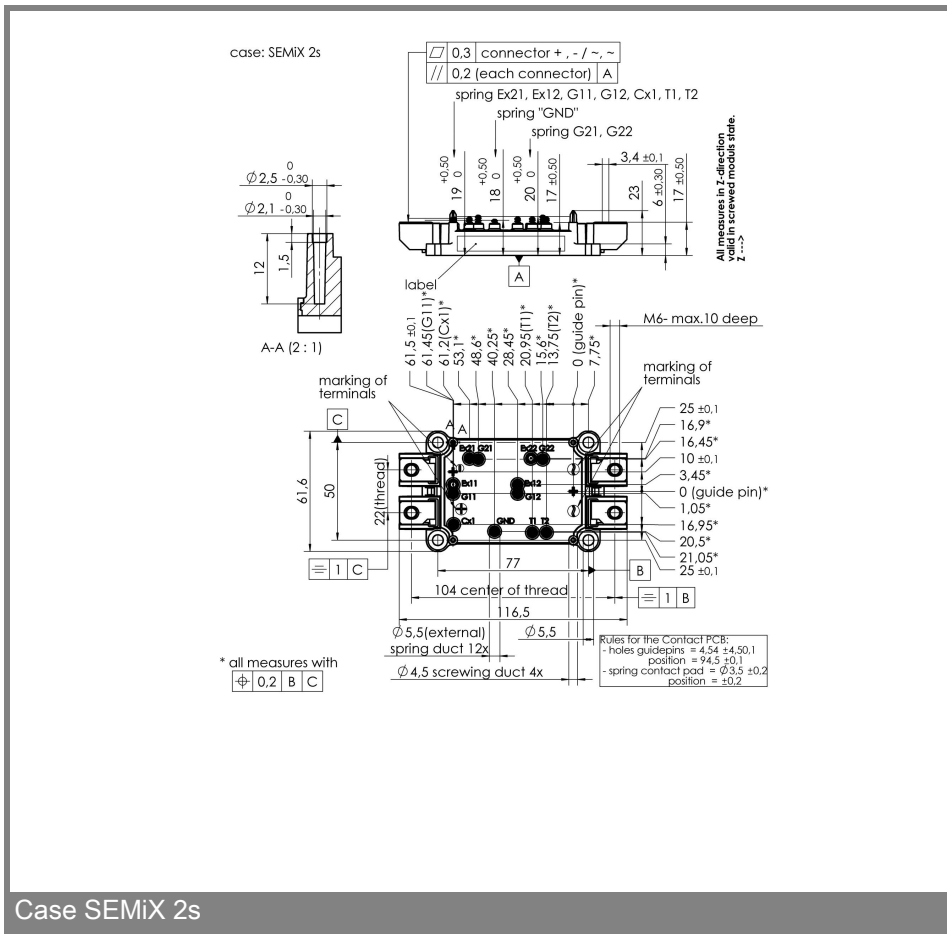
- AC inverter drives
- UPS
- Electronic welders

Absolute Maximum Ratings		$T_{case} = 25^{\circ}C$, unless otherwise specified		
Symbol	Conditions	Values		Units
IGBT				
V_{CES}		1700		V
I_C	$T_c = 25 (80) ^{\circ}C$	320 (230)		A
I_{CRM}	$t_p = 1 ms$	400		A
V_{GES}		± 20		V
$T_{vj}, (T_{stg})$	$T_{OPERATION} \leq T_{stg}$	- 40 ... + 150 (125)		$^{\circ}C$
V_{isol}	AC, 1 min.	4000		V
Inverse diode				
I_F	$T_c = 25 (80) ^{\circ}C$	300 (200)		A
I_{FRM}	$t_p = 1 ms$	400		A
I_{FSM}	$t_p = 10 ms; sin.; T_j = 25 ^{\circ}C$	2000		A

Characteristics		$T_{case} = 25^{\circ}C$, unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
IGBT					
$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 8 mA$	5,2	5,8	6,4	V
I_{CES}	$V_{GE} = 0, V_{CE} = V_{CES}, T_j = 25 (125) ^{\circ}C$			1,6	mA
$V_{CE(TO)}$	$T_j = 25 (125) ^{\circ}C$		1 (0,9)	1,2 (1,1)	V
r_{CE}	$V_{GE} = 15 V, T_j = 25 (125) ^{\circ}C$		5 (7,8)	6,3 (9)	m Ω
$V_{CE(sat)}$	$I_{Cnom} = 200 A, V_{GE} = 15 V, T_j = 25 (125) ^{\circ}C, chip level$		2 (2,45)	2,45 (2,9)	V
C_{ies}	under following conditions		14,2		nF
C_{oes}	$V_{GE} = 0, V_{CE} = 25 V, f = 1 MHz$		0,7		nF
C_{res}			0,6		nF
L_{CE}			18		nH
R_{CC+EE}	terminal-chip, $T_c = 25 (125) ^{\circ}C$				m Ω
$t_{d(on)}/t_r$	$V_{CC} = 1200 V, I_{Cnom} = 200 A$				ns
$t_{d(off)}/t_f$	$V_{GE} = \pm 15 V$				ns
$E_{on} (E_{off})$	$R_{Gon} = R_{Goff} = \Omega, T_j = 125 ^{\circ}C$		130 (70)		mJ
Inverse diode					
$V_F = V_{EC}$	$I_{Fnom} = 200 A; V_{GE} = 0 V; T_j = 25 (125) ^{\circ}C, chip level$		1,7 (1,7)	1,9 (1,9)	V
$V_{(TO)}$	$T_j = 25 (125) ^{\circ}C$		1,1 (0,9)	1,3 (1,1)	V
r_T	$T_j = 25 (125) ^{\circ}C$		3 (4)	3 (4)	m Ω
I_{RRM}	$I_{Fnom} = 200 A; T_j = 25 (125) ^{\circ}C$				A
Q_{rr}	$di/dt = A/\mu s$				μC
E_{rr}	$V_{GE} = -15 V$				mJ
Thermal characteristics					
$R_{th(j-c)}$	per IGBT			0,095	K/W
$R_{th(j-c)D}$	per Inverse Diode			0,17	K/W
$R_{th(j-c)FD}$	per FWD				K/W
$R_{th(c-s)}$	per module		0,045		K/W
Temperature sensor					
R_{25}	$T_c = 25 ^{\circ}C$		5 \pm 5%		k Ω
$B_{25/85}$	$R_2 = R_1 \exp[B(1/T_2 - 1/T_1)]; T[K]; B$		3420		K
Mechanical data					
M_s/M_t	to heatsink (M5) / for terminals (M6)	3/2,5		5 / 5	Nm
w			236		g



SEMIX 302GB176HDs



This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.